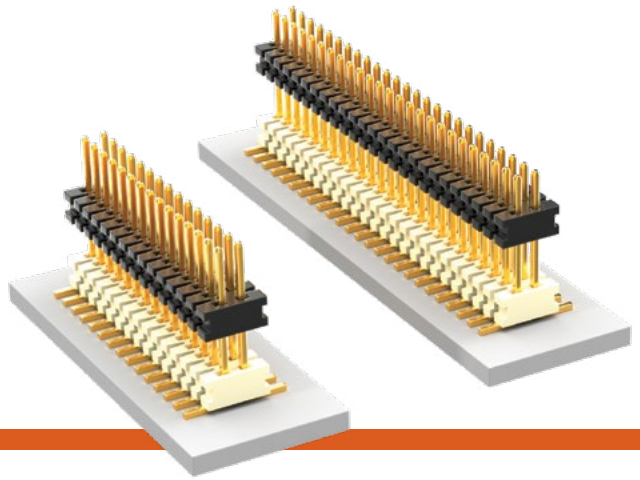
FLEX STACK

SMT MICRO BOARD HEADER

(1.00 mm) .0394" PITCH • MW SERIES



MW
Mates:
CLM, MLE

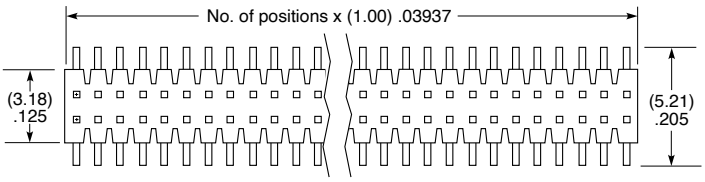
MW	-	NO. PINS PER ROW	-	03	-	PLATING OPTION	-	D	-	STACKER HEIGHT	-	POST HEIGHT	-	OPTION
		02 thru 50				–G = 10 µ" (0.25 µm) Gold				–"XXX" = Stacker Height (in inches) (2.41 mm) .095" to (6.22 mm) .245" Example: –245 = (6.22 mm) .245"		–"XXX" = Post Height (in inches) (1.65 mm) .065" minimum Example: –065 = (1.65 mm) .065"		–A = Alignment Pin (5 positions minimum) Metal or plastic at Samtec's discretion –P = Pick & Place Pad (7 positions minimum) –TR = Tape & Reel –FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks)

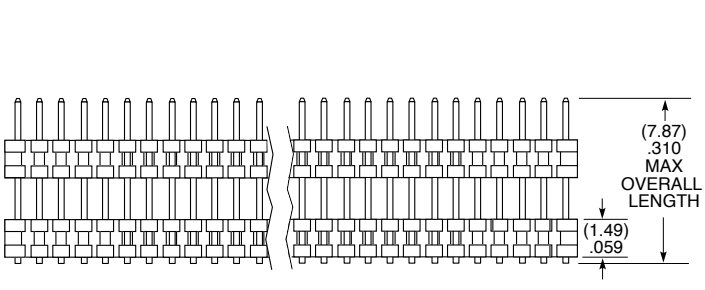
SPECIFICATIONS

Insulator Material:
Top: Black LCP
Bottom: Natural LCP
Terminal Material:
Phosphor Bronze
Plating:
Au over 50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C

PROCESSING

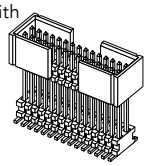
Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-30)
(0.15 mm) .006" max (31-50)*
*(.004" stencil solution may be available; contact ipg@samtec.com)

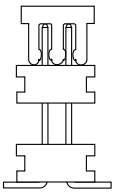




ALSO AVAILABLE
MOQ Required

End shrouds
End shrouds with guide posts



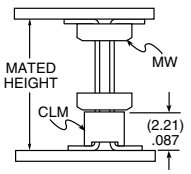


-P OPTION

APPLICATION

EXAMPLES		
LEAD STYLE		MATED HEIGHT*
MW	CLM	
–163-065	-02	(6.35 mm) .250"
–233-065		(8.13 mm) .320"

*Processing conditions will affect mated height.



Notes:
For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.